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Smart Camera System

The Legend 510 machine vision smart camera is a fully functioning CMOS smart camera system. Included are free software licenses and upgrades; free four-day classroom, online and CD-based training; and free global online support. The camera is streamlined to feature the full inspection power of the Legend series without reader capabilities.

DVT Corp., Duluth, GA

Booth 5143



Non-Contact Measuring System

The Hawk non-contact measuring system provides a solution for virtually all measurement applications. High-powered magnification combined with patented Dynascope technology provides users with a clear, pure optical image through the expanded pupil display head. Choose from a range of options including two- or three-axis measurement; manual or motorized movement; manual or fully automated optical and video edge detection (VED); microprocessor or fully geometric PC software; and four stage size options.

Vision Engineering, New Milford, CT

Booth 12084

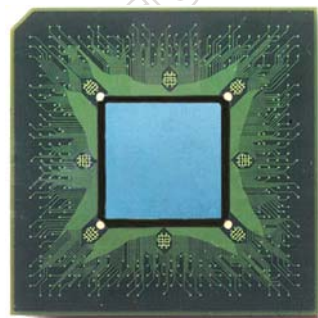


X-Ray Inspection System

The COUGAR versatile x-ray platform (VXP) is a modular inspection platform developed as an x-ray inspection solution to constantly changing market and application requirements in the electronics industry. The system provides a basic platform for further equipment and accessory implementation. Initial configuration includes a standard microfocus x-ray tube up to 160 kV, true x-ray intensity (TXI) control, a four-axes manipulator, a real-time image processing system and a real-time image chain with a high-resolution 4-in. image intensifier and flat-screen monitor.

FEINFOCUS, Stamford, CT

Booth 9300



Flip Chip Capillary Underfill

Hysol FP4547FC capillary flip-chip underfill is compatible with clean and no-clean flux residues. The product protects lead-free flip chip devices and allows them to meet JEDEC Level 3/260°C moisture test requirements. The underfill provides moisture resistance and reduces stress. By incorporating two additives that remove and neutralize flux residues from between the flip chip die and substrate, it meets the new JEDEC requirements for lead-free flip chip assembly, while providing thermal cycle performance and simplifying the assembly process.

Henkel Corp., Industry, CA

Booth 10930

Self-Contained Gas Detectors

STX-PA self-contained gas detection systems are designed to alert personnel to the presence of hazardous gases. Suitable for stand-alone and networked surveillance, the gas monitors feature a local digital display, local audio/visual alarm indicators, programmable dual-level concentration alarms and built-in alarm and system fault relays. They are available for many hazardous gases, including ammonia arsine, phosphine, diborane, chlorine, fluorine, HCl and HF.

*PureAire Monitoring Systems,
Lake Zurich, IL*

Booth 5539

Modular Microscopes

The Z16 APO stereomicroscope offers visual inspection, machine vision and documentation when zero-defect production is essential. The fully apochromatically corrected zoom macrocope has a 16:1 zoom ratio. It can be customized to fit user's needs and is compatible with accessories for examination, training and documentation. Users can couple high-magnification compound objectives so that evaluations can be completed from macro to micro and the same workstation.

*Leica Microsystems Inc.,
Bannockburn, IL*

Booth 10029

High Technology Underfill

The Chipcoat underfill has recent developments for low K die, lead-free bumps and fine-pitch applications. The high-purity insulating materials are used for encapsulation of integrated circuits (ICs) and large-scale integrations (LSIs). The underfill resists moisture and thermal cycles and also has low stress properties.

*NAMICS Technologies Inc.,
Santa Clara, CA*

Booth 9610